

# **Final Product Change Notification**

Issue Date: 21-Mar-2018 Effective Date: 19-Jun-2018

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For detailed information we invite you to view this notification online

# 201710008F01



# **Change Category**

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] Wafer Fab Process	[] Assembly [] Product Marking	[] Test	[] Design
	Process	Location	
] Wafer Fab Materials	[X] Assembly[] Mechanical	[]Test	[] Errata
	Materials Specification	Process	
] Wafer Fab Location	[] Assembly []	[] Test	[] Electrical
	Location Packing/Shipping/Labeling Equipment		spec./Test
			coverage

ASECL LQFP 14x14 100L Qualification with Sumitomo G631HA Molding Compound and New Lead Frame

# **Details of this Change**

NXP Semiconductors announces a mold compound change from CEL9240HF10AK to Sumitomo G631HA LQFP 14X14 100L for the products listed in the notification, currently assembled at the ASE-Chungli Taiwan (ASECL) Assembly Site. There is no change to the package outline dimensions.

A new lead frame was qualified with no change to lead frame materials. The flag size for STMP3770XXLAEA3N, DSP56F803BU80E, and DSP56F826BU80E will change from 6.1x6.1 mm to 5.5x5.5 mm.

#### Why do we Implement this Change

The molding compound change to Sumitomo G631HA from CEL9240HF10AK is required for supply assurance and standardization of Bill Of Material in ASECL assembly site.

### **Identification of Affected Products**

Top side marking

Please refer to the attachment for detail

# **Product Availability**

# Sample Information

Samples are available upon request

#### **Production**

Planned first shipment 20-Jun-2018

#### Impact

There is no change to product form, fit, function, or reliability

**Disposition of Old Products** 

Existing inventory will be shipped until depleted

# **Timing and Logistics**

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 20-Apr-2018.

#### **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Position Product Engineer
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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest

possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

# **About NXP Semiconductors**

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# **Affected Part Numbers**

MK60DN256ZVLL10

DSP56F826BU80E

MK20DN512ZVLL10

MK10DN512ZVLL10

DSP56F803BU80E

MK60DN512ZVLL10